

L Number	Hits	Search Text	DB	Time stamp
1	5139	(chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:38
2	3933	((chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and (@ad<20010718)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:53
3	10	((chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and (@ad<20010718)) and ((warp\$4 or bend\$3) with ((electrode or terminal or pad) with (polymer or photopolymer\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:59
4	2	((chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and (@ad<20010718)) and ((warp\$4 or bend\$3) with ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and bak\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:34
5	0	((chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and (@ad<20010718)) and ((warp\$4 or bend\$3) with bak\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:37
6	4	((chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and (@ad<20010718)) and ((warp\$4 or bend\$3) same bak\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:40
8	1503	((chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and (@ad<20010718)) and ((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:51
9	292	((chip or die) and ((electrode or terminal or pad) with (polymer or photopolymer\$4))) and (@ad<20010718)) and ((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4))) and (warp\$4 or bend\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:52
10	225652	((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4))) and (warp\$4 or bend\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:51
11	18913	((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4))) and (warp\$4 or bend\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:52
12	5952	((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4))) and (warp\$4 or bend\$3) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:53
13	4704	((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4))) and (warp\$4 or bend\$3) and (chip or die) and (@ad<20010718)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 15:53
14	1156	((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4))) and (warp\$4 or bend\$3) and (chip or die) and (@ad<20010718)) and ((warp\$4 or bend\$3) same (electrode or terminal or pad))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/27 16:04

15	667	(((((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4)))) and (warp\$4 or bend\$3) ) and (chip or die)) and (@ad<20010718)) and ((warp\$4 or bend\$3) same (electrode or terminal or pad)) ) and (ball\$1 or bump\$1 solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 16:05
16	667	(((((bak\$3 or heat\$2) with ((electrode or terminal or pad) or (polymer or photopolymer\$4)))) and (warp\$4 or bend\$3) ) and (chip or die)) and (@ad<20010718)) and ((warp\$4 or bend\$3) same (electrode or terminal or pad)) ) and (ball\$1 or bump\$1 or solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/27 16:05